



Image

Attorney's Docket No.: 12816-021001 / S1166 SB/flu

2814
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Detlef Weber
Serial No. : 09/898,909
Filed : July 3, 2001
Title : METALLIZATION ARRANGEMENT FOR SEMICONDUCTOR STRUCTURE
AND CORRESPONDING FABRICATION METHOD

Art Unit : 2814
Examiner : P. Cao

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

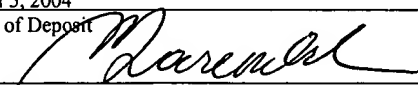
AMENDMENT IN REPLY TO ACTION OF DECEMBER 3, 2004

Please amend the above-identified application as follows:

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

April 5, 2004
Date of Deposit


Signature

Iria Zarembok
Typed or Printed Name of Person Signing Certificate